

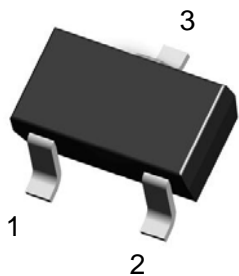
N-Channel Enhancement-Mode MOSFET (30V, 5.8A)

PRODUCT SUMMARY		
V_{DSS}	I_D	$R_{DS(on)}$ (m Ω) Max
30V	5.8A	28 @ $V_{GS} = 10V, I_D=5.8A$
		43 @ $V_{GS} = 4.5V, I_D=5.0A$

Features

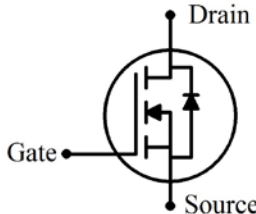
- Advanced Trench Process Technology
- High Density Cell Design for Ultra Low On-Resistance
- Rugged and reliable.
- Ordering information: GN3404-G(Lead(Pb)-free and halogen-free)





GN3404 Pin Assignment & Symbol

3-Lead Plastic **SOT-23**
Pin 1: Gate 2: Source 3: Drain



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current (Continuous)	$T_A=25^\circ\text{C}$	5.8
		$T_A=70^\circ\text{C}$	4.9
I_{DM}	Drain Current (Pulsed) ^a	20	A
P_D	Total Power Dissipation $T_A=25^\circ\text{C}$	1.4	W
T_j, T_{stg}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (PCB mounted) ^b	90	$^\circ\text{C/W}$

Note: a: Repetitive Rating: Pulse width limited by the maximum junction temperature.
 b: 1-in² 2oz Cu PCB board

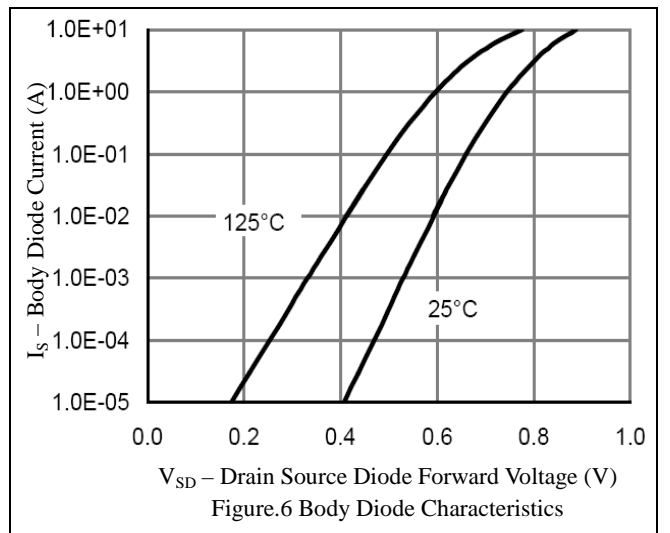
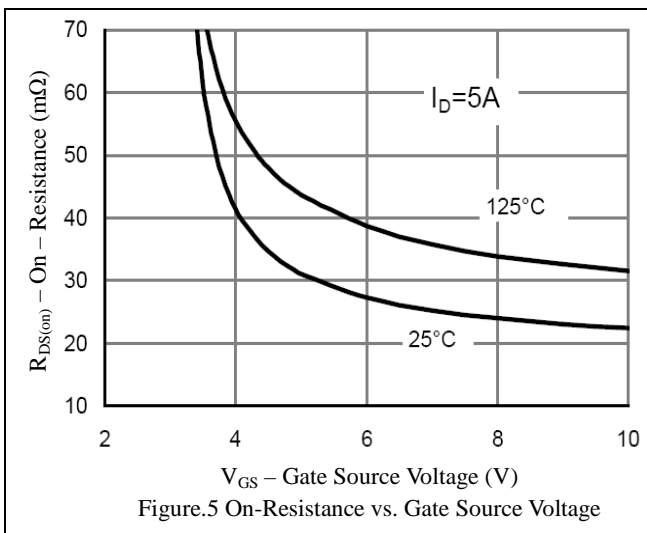
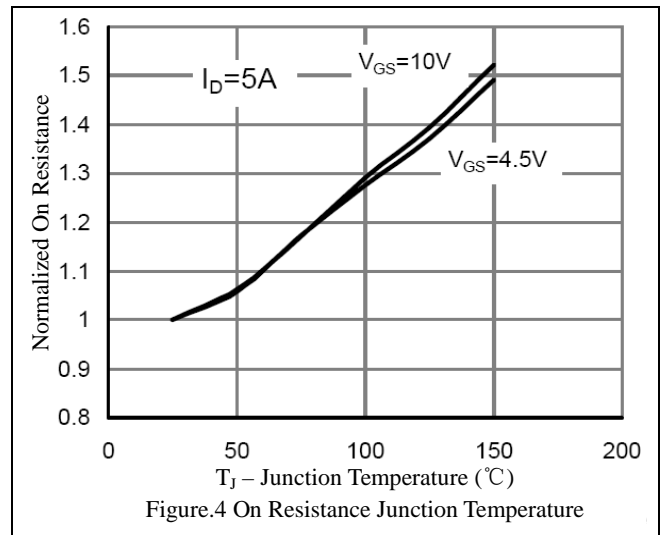
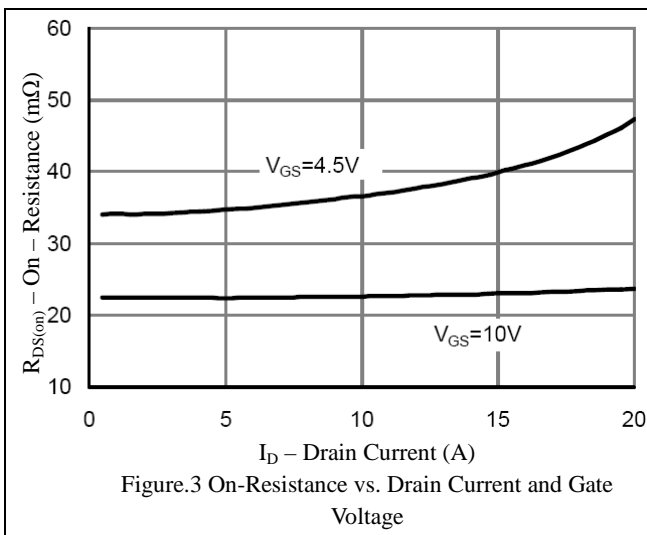
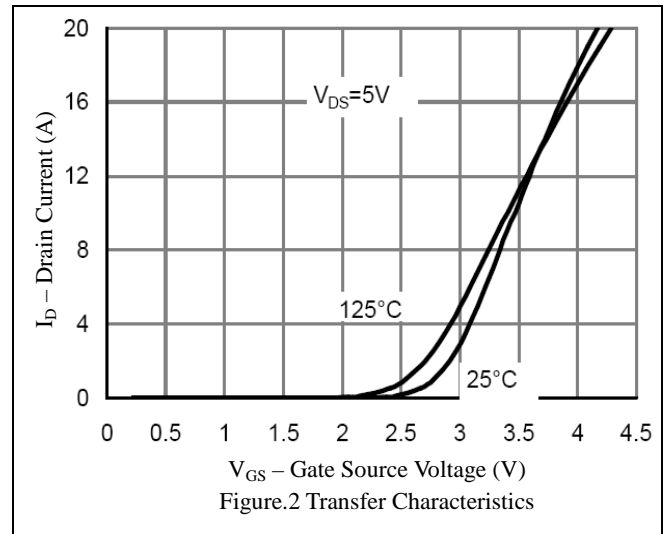
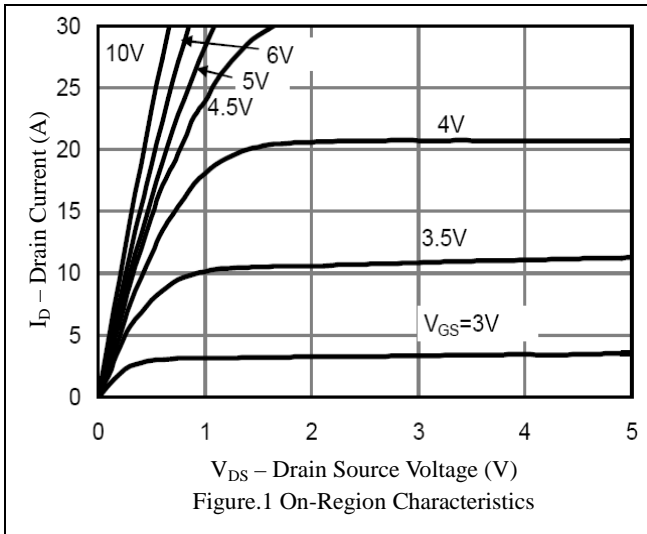
Electrical Characteristics (T_A=25°C, unless otherwise noted)

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
• Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V	-	-	1	μA
		V _{DS} =24V, V _{GS} =0V, T _J =55°C	-	-	5	
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
• On Characteristics ^c						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1	-	3	V
I _{D(on)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	20	-	-	A
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =5.8A	-	22.5	28	mΩ
		V _{GS} =4.5V, I _D =5A	-	34.5	43	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =5.8A	-	14.5	-	S
• Dynamic Characteristics ^d						
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	-	680	-	pF
C _{oss}	Output Capacitance		-	102	-	
C _{rss}	Reverse Transfer Capacitance		-	77	-	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	1.5	3	3.6	Ω
• Switching Characteristics ^d						
Q _{g(10)}	Total Gate Charge(10V)	V _{DS} =15V, I _D =5.8A, V _{GS} =10V	-	13.88	-	nC
Q _{g(4.5)}	Total Gate Charge(4.5V)		-	6.78	-	
Q _{gs}	Gate-Source Charge		-	1.8	-	
Q _{gd}	Gate-Drain Charge		-	3.12	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} =15V, R _L =2.7Ω, V _{GS} =10V, R _{GEN} =3Ω	-	4.6	-	nS
t _r	Turn-on Rise Time		-	3.8	-	
t _{d(off)}	Turn-off Delay Time		-	20.9	-	
t _f	Turn-off Fall Time		-	5	-	
t _{rr}	Body Diode Reverse Recovery Time	I _F =5.8A, dI/dt=100A/μs	-	16.1	-	nS
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =5.8A, dI/dt=100A/μs	-	7.4	-	nC
• Drain-Source Diode Characteristics						
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} =0V, I _S =1A	-	-	1	V
I _S	Maximum Body-Diode Continuous Current		-	-	2.5	A
	Pulsed Body-Diode Current		-	-	20	A

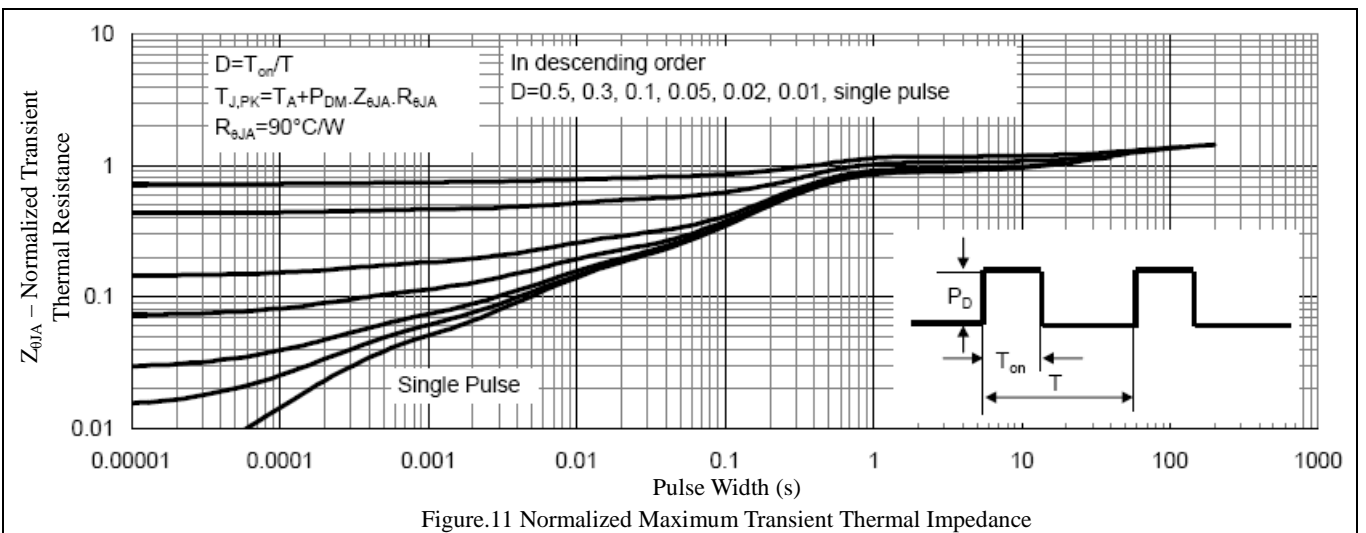
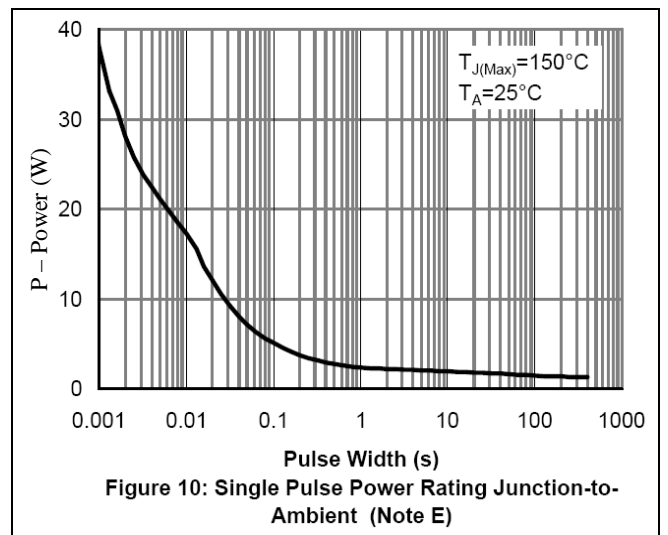
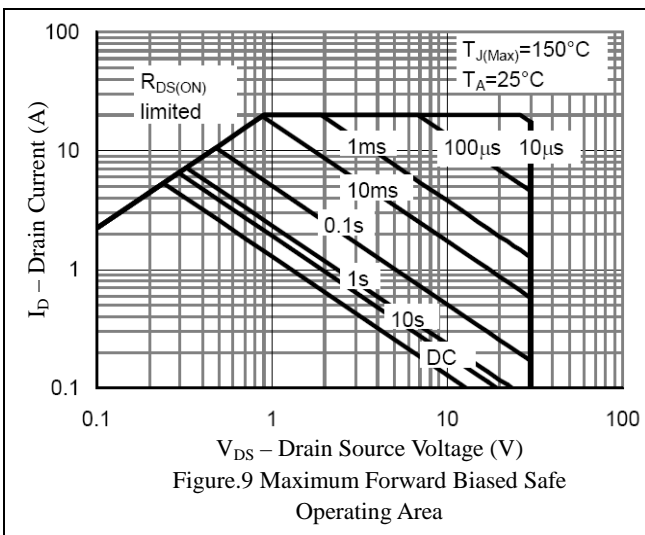
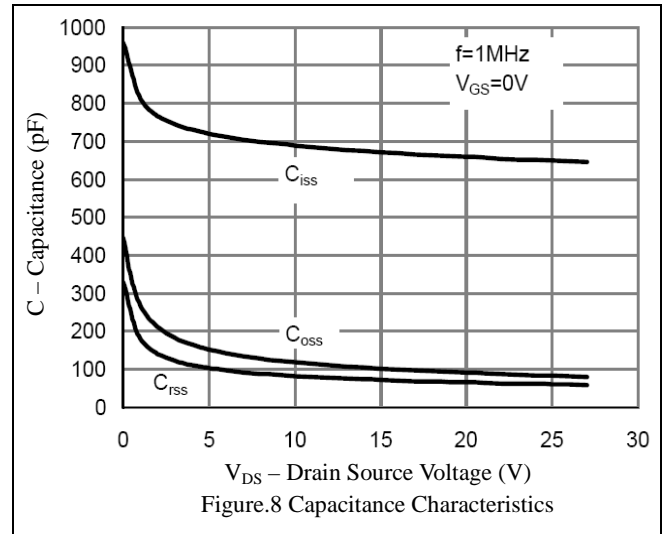
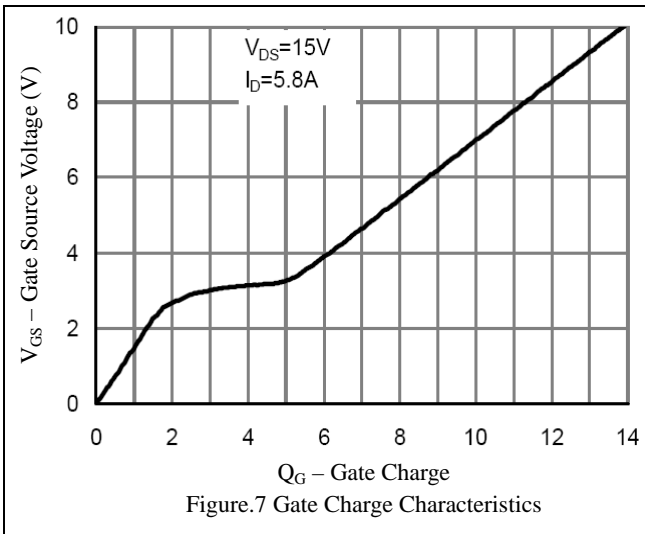
Note: c: Pulse Test : Pulse Width < 300μs, Duty Cycle < 2%

d: Guaranteed by design, not subject to production testing.

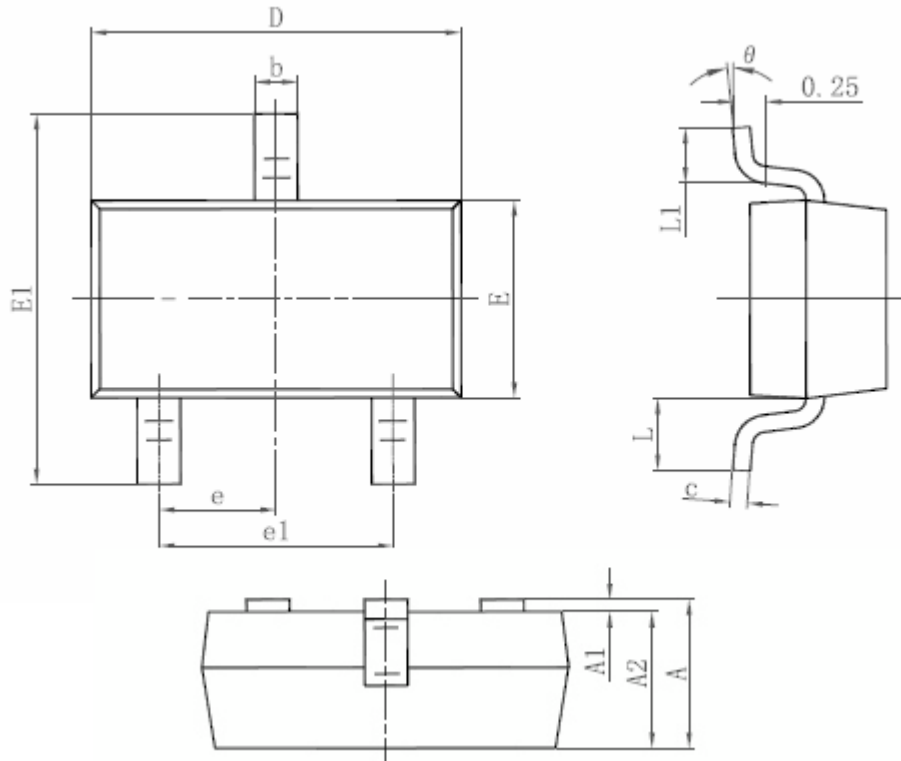
Characteristics Curve



Characteristics Curve



SOT-23 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°



Notice

1. Specification of the products displayed herein is subject to change without notice. Continuous development may necessitate changes in technical data without notice. GEMMICRO or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies.
2. Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.